

# INTERNATIONAL STANDARD

## NORME INTERNATIONALE

**Materials for printed boards and other interconnecting structures –  
Part 2-39: Reinforced base materials clad and unclad – High performance  
epoxide and non-epoxide, woven E-glass laminate sheets of defined  
flammability (vertical burning test), copper-clad for lead-free assembly**

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**Matériaux pour circuits imprimés et autres structures d'interconnexion –  
Partie 2-39: Matériaux de base renforcés, plaqués et non plaqués – Feuilles  
stratifiées en tissu de verre de type E époxyde et non époxyde à haute  
performance, plaquées cuivre, d'inflammabilité définie (essai de combustion  
verticale), pour les assemblages sans plomb**



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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**MATERIALS FOR PRINTED BOARDS AND  
OTHER INTERCONNECTING STRUCTURES –**

**Part 2-39: Reinforced base materials clad and unclad –  
High performance epoxide and non-epoxide, woven E-glass  
laminated sheets of defined flammability (vertical burning test),  
copper-clad for lead-free assembly**

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International Standard IEC 61249-2-39 has been prepared by IEC technical committee 91: Electronics assembly technology.

The text of this standard is based on the following documents:

FDIS	Report on voting
91/1052/FDIS	91/1065/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts of the IEC 61249 series, under the general title *Materials for printed boards and other interconnecting structures*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC web site under "http://webstore.iec.ch" in the data related to the specific publication. At this date, the publication will be

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## MATERIALS FOR PRINTED BOARDS AND OTHER INTERCONNECTING STRUCTURES –

### Part 2-39: Reinforced base materials clad and unclad – High performance epoxide and non-epoxide, woven E-glass laminate sheets of defined flammability (vertical burning test), copper-clad for lead-free assembly

#### 1 Scope

This part of IEC 61249 specifies requirements for properties of modified brominated epoxide woven E-glass laminated sheet of a thickness 0,05 mm up to 3,2 mm, of defined flammability (vertical burning test), copper-clad. The glass transition temperature is defined to be 170 °C minimum.

Its flame resistance is defined in terms of the flammability requirements of 7.3.

Some property requirements may have several classes of performance. The class desired should be specified on the purchase order, otherwise the default class of material will be supplied.

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#### 2 Normative references

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 61189-2:2006, *Test methods for electrical materials, printed boards and other interconnection structures and assemblies – Part 2: Test methods for materials and other interconnection structures*

IEC 61249-5-1:1995, *Materials for interconnection structures – Part 5: Sectional specification set for conductive foils and films with or without coatings – Section 1: Copper foils (for the manufacture of copper-clad base materials)*

IEC/PAS 61249-6-3:2011, *Specification for finished fabric woven from E-glass for printed boards*

ISO 11014:2009, *Safety data sheet for chemical products – Content and order of sections*

#### 3 Materials and construction

##### 3.1 General

The sheet consists of an insulating base with metal-foil bonded to one side or both.

##### 3.2 Resin system

A blend of majority di-functional, multifunctional epoxide and non-epoxide, woven E-glass laminate with a glass transition temperature of 170 °C minimum. The flammability rating is achieved through the use of bromine reacted into the polymer. Inorganic fillers may be used.



Contrast agents may be added to enhance processing such as automated optical inspection (AOI).

The maximum total halogens contained in resin plus reinforcement matrix is 1 500 ppm with a maximum chlorine of 900 ppm and maximum bromine of 900 ppm.

Its flame resistance is defined in terms of the flammability requirements of 7.3.

### 3.3 Metal foil

Copper, as specified in IEC 61249-5-1, copper foil (for the manufacture of copper-clad materials). The preferred foils are electrodeposited of defined ductility.

### 3.4 Reinforcement

Woven E-glass as specified in IEC/PAS 61249-6-3, woven E-glass fabric (for the manufacture of prepreg and copper clad materials).

## 4 Internal marking

Not specified.

## 5 Electrical properties

The electrical property requirements are shown in Table 1.

**Table 1 – Electrical properties**

Property	Test method IEC 61189-2	Requirement
Resistance of foil	2E12	As specified in IEC 61249-5-1
Surface resistance after damp heat while in the humidity chamber (optional)	2E03	$\geq 10\,000\ \text{M}\Omega$
Surface resistance after damp heat and recovery	2E03	$\geq 50\,000\ \text{M}\Omega$
Volume resistivity after damp heat while in the humidity chamber (optional)	2E04	$\geq 5\,000\ \text{M}\Omega\text{m}$
Volume resistivity after damp heat and recovery	2E04	$\geq 10\,000\ \text{M}\Omega\text{m}$
Relative permittivity after damp heat and recovery (1 MHz)	2E10	$\leq 5,4$
Dissipation factor after damp heat and recovery (1 MHz)	2E10	$\leq 0,035$
Electric strength (only for material thickness less than 0,5 mm)	2E11	$\geq 30\ \text{kV/mm}$
Arc resistance	2E14	$\geq 60\ \text{s}$
Dielectric breakdown (only for material thicknesses $\geq 0,5\ \text{mm}$ )	2E15	$\geq 40\ \text{kV}$
Surface resistance at 125 °C	2E07	$\geq 1\,000\ \text{M}\Omega$
Volume resistivity at 125 °C	2E07	$\geq 1\,000\ \text{M}\Omega\text{m}$

## 6 Non-electrical properties of the copper-clad laminate

### 6.1 Appearance of the copper-clad sheet

#### 6.1.1 General

The copper-clad face shall be substantially free from defects that may have an impact on the material's fitness for use for the intended purpose.

For the following specific defects the requirements given shall apply when inspection is made in accordance with IEC 61189-2, method 2M18.

#### 6.1.2 Indentations (pits and dents)

The size of an indentation, usually the length, shall be determined and given a point value to be used as measure of the quality, see Table 2.

**Table 2 – Indentations**

Size mm	Point value for each indentation
0,13 – 0,25	1
0,26 – 0,50	2
0,51 – 0,75	4
0,76 – 1,00	7
>1,00	30

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The total point count for any 300 mm × 300 mm area shall be calculated to determine the class of the material.

Class A	29 maximum
Class B	17 maximum
Class C	5 maximum
Class D	0
Class X	To be agreed upon by user and supplier

The required class of material shall be specified in the purchase order. Class A applies unless otherwise specified.

#### 6.1.3 Wrinkles

There shall be no wrinkles in the copper surface.

#### 6.1.4 Scratches

Scratches deeper than 20 % of the nominal thickness of the foil thickness are not permitted.

Scratches with a depth less than 5 % of the nominal thickness of the foil shall not be counted unless this depth is 10 µm or more.

Scratches with a depth between 5 % and 20 % of the nominal thickness of the foil are permitted to a total length of 100 mm for a 300 mm × 300 mm area.

### 6.1.5 Raised areas

Raised areas are usually impressions in the press plates used during manufacture, but may also be caused by blisters or inclusions of foreign particles under the foil.

Raised areas caused by blisters or inclusions are not permitted.

Raised areas being impressions of defects in press plates are permitted to the following extent:

Class A and X material	Maximum height 15 $\mu\text{m}$ and maximum length 15 mm
Class B and C material	Maximum height 8 $\mu\text{m}$ and maximum length 15 mm
Class D material	Maximum height 5 $\mu\text{m}$ and maximum length 15 mm

### 6.1.6 Surface waviness

When examined in accordance to test method 2M12 of IEC 61189-2, the surface waviness in both the machine and cross-machine direction shall not exceed 7  $\mu\text{m}$ .

## 6.2 Appearance of the unclad face

The unclad face of single side clad sheet shall have the natural appearance resulting from the curing process. Small irregularities in colour are permitted. The gloss of the unclad face shall be that given by the press plate or release foil used. Variations of gloss due to the impact of pressure of gases released during the curing are permitted.

## 6.3 Laminate thickness

The laminate thickness may be ordered to include or exclude the copper foil contribution as specified in the purchase order. As a general rule laminates less than 0,8 mm are measured excluding copper and laminates greater or equal to 0,8 mm are measured including copper. If the copper-clad laminate is tested in accordance with test method 2D01 of IEC 61189-2, the thickness shall not depart from the nominal thickness by more than the appropriate value shown in Table 3. The fine tolerances shall apply unless the other tolerances are ordered.

**Table 3 – Nominal thickness and tolerance of metal-clad laminate**

Nominal thickness excluding metal foil (material intended for multilayer boards) mm	Nominal thickness including metal foil (material intended for single or double sided boards) mm	Tolerance requirement $\pm$ mm		
		Coarse	Fine	Extra fine
$\geq 0,05 \leq 0,10$		0,03	0,02	0,01
$> 0,10 \leq 0,15$		0,04	0,03	0,02
$> 0,15 \leq 0,30$		0,05	0,04	0,03
$> 0,30 \leq 0,50$		0,08	0,05	0,04
$> 0,50 \leq 0,80$		0,09	0,06	0,05
$> 0,80 \leq 1,00$	$\geq 0,80 \leq 1,00$	0,13	0,09	0,07
$> 1,00 \leq 1,30$	$> 1,00 \leq 1,30$	0,17	0,11	0,08
	$> 1,30 \leq 1,70$	0,20	0,13	0,10
	$> 1,70 \leq 2,10$	0,23	0,15	0,12
	$> 2,10 \leq 2,60$	0,25	0,18	0,15
	$> 2,60 \leq 3,20$	0,30	0,20	0,15

The thickness and tolerances do not apply to the outer 25 mm of the trimmed master sheet or the outer 13 mm of the cut-to-size panel as manufactured and delivered by the supplier. At no

point shall the thickness vary from the nominal value by more than 125 % of the specified tolerance.

#### 6.4 Bow and twist

When the copper-clad laminate is tested in accordance with test method 2M01 of IEC 61189-2 the bow and twist shall not exceed the values given in Table 4.

**Table 4 – Bow and twist requirements**

Property	Test method IEC 61189-2	Nominal thickness mm	Panel dimension longest side mm	Requirement %	
				Copper foil on one side	Copper foil on both sides
Bow and twist	2M01	≥0,8 ≤ 1,3	≤350	≤2,0	≤1,5
			>350 ≤ 500	≤1,8	≤1,3
			>500	≤1,5	≤1,0
		>1,3 < 1,7	≤350	≤1,5	≤1,0
			>350 ≤ 500	≤1,3	≤0,8
			>500	≤1,0	≤0,5
		≥1,7 ≤ 3,2	≤350	≤1,0	≤0,5
			>350 ≤ 500	≤0,8	≤0,4
			>500	≤0,5	≤0,3

NOTE The requirements for bow and twist apply only to one-sided copper-clad laminates with maximum foil thickness of 105 μm (915 g/m<sup>2</sup>) and double-sided copper-clad laminates with maximum foil thickness difference of 70 μm (610 g/m<sup>2</sup>).

Requirements for laminates with copper foil configurations beyond these limits are subject to agreement between purchaser and supplier.

#### 6.5 Properties related to the copper foil bond

Pull-off and peel strength requirements are shown in Table 5. These requirements apply to copper foil with a normal profile depth. In the case of low or very low profile copper foil, the requirements shall be at least 50 % of that shown in Table 5 as a minimum.

**Table 5 – Pull-off and peel strength requirements**

Property	Test method IEC 61189-2	Requirements			
Pull-off strength	2M05	≥25 N			
		Thickness of the copper foil			
		≤12 μm (≤101 g/m <sup>2</sup> )	18 μm (152 g/m <sup>2</sup> )	35 μm (305 g/m <sup>2</sup> )	≥70 μm (≥610 g/m <sup>2</sup> )
Peel strength after heat shock of 20 s	2M14	≥0,7 N/mm	≥0,9 N/mm	≥1,2 N/mm	≥1,6 N/mm
		No blistering or delamination			
Peel strength after dry heat 125 °C	2M15	≥0,7 N/mm	≥0,9 N/mm	≥1,2 N/mm	≥1,6 N/mm
		No blistering or delamination			
Peel strength after exposure to solvent vapour. Solvents as agreed upon between purchaser and supplier	2M06	≥0,7 N/mm	≥0,9 N/mm	≥1,2 N/mm	≥1,6 N/mm
		No blistering no delamination			
Peel strength after simulated plating	2M16	≥0,6 N/mm	≥0,8 N/mm	≥1,0 N/mm	≥1,2 N/mm
		No blistering no delamination			
Peel strength at high temperature Temperature 125 °C (optional)	2M17	Not specified	≥0,7 N/mm	≥0,9 N/mm	≥1,1 N/mm
Blistering after 20 s heat shock	2C05	No blistering no delamination			
In case of difficulty due to breakage of the foil or reading range of the force measuring device, the measurement of peel strength at high temperature may be carried out using conductor widths of more than 3 mm.					

## 6.6 Punching and machining

Punching is not applicable. The laminate shall, in accordance with the manufacturer's recommendations, be capable of being sheared or drilled. Delamination at the edges due to the shearing process is permissible, provided that the depth of delamination is not larger than the thickness of the base material. Delamination at the edges of drilled holes due to the drilling process is not permissible. Drilled holes shall be capable of being through-plated with no interference from any exudations into the hole.

## 6.7 Dimensional stability

The dimensional stability requirements are shown in Table 6. When specimens are tested in accordance to IEC 61189-2, method 2X02 the observe tolerance shall be as specified in Table 6. The nominal dimensional stability value shall be as agreed upon between user and vendor. The tolerance range around the agreed upon nominal value shall be Class A, unless otherwise specified on the purchase order.

The choice of the glass fabrics in the construction of the laminate has a significant impact on dimensional stability. Examples of typical constructions used in printed board applications can be found in Annex B.

**Table 6 – Dimensional stability**

Property	Test method IEC 61189-2	Class	Requirement ppm
Dimensional stability	2X02	A	±300
		B	±200
		C	±100
		X	As agreed upon between user and supplier

**6.8 Sheet sizes**

**6.8.1 Typical sheet sizes**

Sheet sizes are matters of agreement between purchaser and supplier. However, the recommended sizes are listed below:

- 915 mm × 1 220 mm;
- 1 065 mm × 1 155 mm;
- 1 065 mm × 1 280 mm;
- 1 000 mm × 1 000 mm;
- 1 000 mm × 1 200 mm

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**6.8.2 Tolerances for sheet sizes**

The size of sheet delivered by the supplier shall not deviate by more than +20/–0 mm from the ordered size.

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**6.9 Cut panels**

**6.9.1 Cut panel sizes**

Cut panel sizes shall be, when delivered, in accordance with the purchaser’s specification.

**6.9.2 Size tolerances for cut panels**

For panels cut to size according to the purchaser’s specification, the following tolerances for length and width shall apply, as shown in Table 7. Tolerances indicated as normal shall be in effect unless otherwise specified by in the purchasing specification.

**Table 7 – Size tolerances for cut panels**

Panel size mm	Tolerance requirement ± mm	
	Normal	Close
≤300	2,0	0,5
>300 ≤ 600	2,0	0,8
>600	2,0	1,6

NOTE The specified tolerances include all deviations caused by cutting the panels.

### 6.9.3 Rectangularity of cut panels

For panels cut to size according to the purchaser's specification, the following requirements for rectangularity shall apply as shown in Table 8. Tolerance indicated as normal shall be in effect unless otherwise specified in the purchasing specification.

**Table 8 – Rectangularity of cut panels**

Property	Test method IEC 61189-2	Requirement mm/m	
		Normal	Close
Rectangularity of cut panels	2M23	≤3	≤2

## 7 Non-electrical properties of the base material after complete removal of the copper foil

### 7.1 Appearance of the dielectric base material

The etched specimens shall be inspected to verify that no surface or subsurface imperfections of the dielectric material exceed those shown below. The panels shall be inspected using an optical aid apparatus which provides a minimum magnification of 4X.

Referee inspection shall be conducted at 10X magnification. Lighting conditions of inspection shall be appropriate to the material under inspection or as agreed upon between user and supplier.

Surface and subsurface imperfections (such as weave texture, resin starvation, voids, foreign inclusions) shall be acceptable provided that the imperfections meet the following:

- the reinforcement fibres are not cut or exposed;
- the foreign inclusions are not conductive;
- the imperfections do not propagate as a result of thermal stress;
- the foreign inclusions are translucent;
- opaque foreign fibres are less than 15 mm in length and average no more than 1,0 per 300 mm × 300 mm area;
- opaque foreign inclusions other than fibres shall not exceed 0,50 mm. Opaque foreign inclusions less than 0,15 mm shall not be counted. Opaque foreign inclusions between 0,50 mm and 0,15 mm shall average no more than two spots per 300 mm × 300 mm area;
- voids (sealed voids or surface void) have a longest dimension less than 0,075 mm and there should not be more than three voids in a 3,5 mm diameter circle.

### 7.2 Flexural strength

When the laminate is tested in accordance with test method 2M20 of IEC 61189-2, the flexural strength shall be as shown in Table 9.